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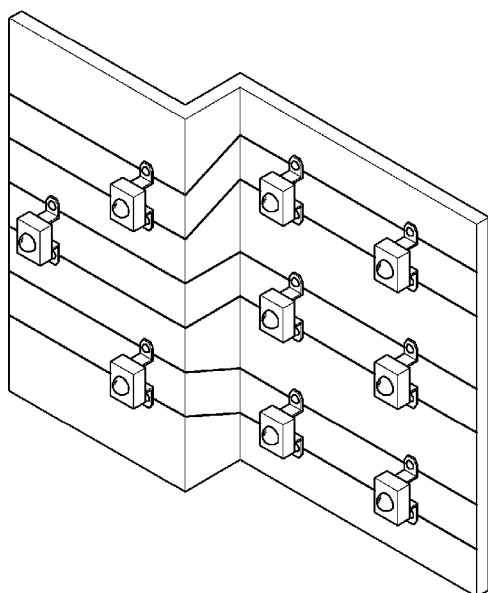
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[Continued on next page]

(54) Title: LED LAMP



(57) Abstract: The present invention relates to a light emitting diode (LED) lamp, and an object of the present invention is to provide an LED lamp in which an LED can be easily exchanged and external vibration can be absorbed to prevent the play thereof. To this end, an LED lamp according to the present invention comprises an LED package having a lead frame; a printed circuit board separated from the LED package and having a conductive pattern formed on a surface thereof facing the lead frame; and a pressing means for pressing the LED package toward the PCB so that the lead frame is in contact with the conductive pattern.

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Description

LED LAMP

Technical Field

- [1] The present invention relates to a light emitting diode (LED) lamp, and more particularly, to an LED lamp in which an LED can be easily exchanged and external vibration can be absorbed to prevent the play thereof.

Background Art

- [2] Generally, an LED is an electronic device that emits light through recombination of injected minority carriers (electrons or holes) using a p-n junction of a semiconductor. That is, when electric power is applied to a semiconductor of a specific element in a forward direction, electrons and holes move through the junction of positive and negative electrodes, and are recombined with each other and then have energy lower than those of separate electrons and holes. Due to difference in energy generated at this time, light is emitted.
- [3] Such an LED has a smaller size and a longer life span and can emit light with high efficiency using a lower voltage as compared with conventional light sources. In particular, since LEDs have a rapid response property, they are widely used for indicator lamps or digit indicators of various electronic equipment, such as indicators of instrument panels of automobiles or light sources for fiber optic communication, and also applied in different manners as lighting means for houses, vehicles, ships, traffic signals, a variety of guide lights, exit sign lights, and the like.
- [4] Fig. 1 is a perspective view showing a printed circuit board (PCB) to which LED chips are mounted using surface mount technology, and Fig. 2 is a perspective view showing a PCB to which LED packages are mounted by means of clinching.
- [5] Since a single LED chip or package cannot give sufficient illuminance and luminance, an LED lamp includes about 20 or more LED chips or packages (the number thereof varies depending on use of the lamp) that are arranged in parallel or in series to form a circuit.
- [6] Among LED lamps, the LED lamp of Fig. 1 is manufactured using surface mount technology (SMT) in such a manner that LED chips are mounted directly on a PCB and then fixed thereto by means of soldering.
- [7] However, in the LED lamp manufactured using SMT as described above, there is inconvenience in that if an LED chip is out of order, solder used for fixing the LED chip should be removed and then a new LED chip should be soldered again upon mounting thereof. In addition, if external vibration is applied thereto, there is a high possibility that a copper plate of the PCB will be separated due to the vibration.

[8] Meanwhile, the LED lamp of Fig. 2, which is made by means of clinching, does not require additional soldering since lead frames of the LED package are attached to the PCB by means of clinching.

[9] However, since the LED lamp made by means of clinching has a plurality of LED packages connected in series, the LED lamp has a disadvantage in that the entire module should be replaced even though only one LED package is out of order. In addition, since the LED packages are attached through clinching, there is a high possibility that a circuit on the PCB will be short-circuited.

Disclosure of Invention

Technical Problem

[10] Accordingly, the present invention is conceived to solve the aforementioned problems. It is an object of the invention to provide an LED lamp in which LED packages are provided separately from a PCB, lead frames of each of the LED packages can be always in contact with the PCB, and the LED package can be easily replaced when required.

[11] In addition, another object of the present invention is to provide an LED lamp provided with an elastic member for elastically biasing LED packages toward a PCB so that the LED packages or the PCB is not influenced by external vibration.

Technical Solution

[12] An LED lamp according to the present invention comprises an LED package having a lead frame; a printed circuit board separated from the LED package and having a conductive pattern formed on a surface thereof facing the lead frame; and a pressing means for pressing the LED package toward the PCB so that the lead frame is in contact with the conductive pattern.

[13] A fixing hole may be formed in one of the lead frame and the PCB, and a fixing member that is to be at least partially inserted into the fixing hole may be formed on the other one of the lead frame and the PCB. A heat sink may be formed on a lower surface of the LED package such that the heat sink is exposed outward, a heat dissipation plate may be provided at a position spaced apart by a predetermined distance from the heat sink, and the pressing means may be installed to be interposed between and brought contact with the heat sink and the heat dissipation plate. The pressing means may comprise an elastic member. A fixing shaft for fixing the elastic member may protrude upward from an upper portion of the heat dissipation plate.

[14] The PCB may comprise first and second PCBs that are separate from and spaced apart from each other so that the LED package is exposed in a light emitting direction. Alternatively, the PCB may have an opening portion for exposing the LED package in a light emitting direction.

Advantageous Effects

- [15] Since the LED lamp of the present invention includes the LED package and the PCB that are separate from each other and is constructed such that the lead frame of the LED package can be always in contact with the PCB, it is possible to replace only a desired LED package, if necessary. In addition, since the LED lamp of the present invention includes the elastic member between the heat dissipation plate and LED package, even when external vibration is applied, the vibration is prevented from being transmitted to the LED package or PCB.

Brief Description of the Drawings

- [16] Fig. 1 is a perspective view showing a PCB to which LED chips are mounted using surface mount technology.
- [17] Fig. 2 is a perspective view showing a PCB to which LED packages are mounted by means of clinching.
- [18] Fig. 3 is a perspective view showing an LED lamp according to an embodiment of the present invention.
- [19] Fig. 4 is a sectional view showing the LED lamp of Fig. 3.
- [20] Fig. 5 is a plan view showing an LED lamp according to another embodiment of the present invention.
- [21] <Explanation of Reference Numerals for Main Portions in Drawings>
- [22] 110: LED package 112: Metal slug
- [23] 113: Concave portion 114: LED chip
- [24] 115: Wire 116: Lead frame
- [25] 117: Insulation film 118: Molding portion
- [26] 119: Fixing member 120: Printed circuit board
- [27] 122: Conductive pattern 124: Fixing hole
- [28] 130: Heat dissipation plate 140: Elastic member

Best Mode for Carrying Out the Invention

- [29] Hereinafter, preferred embodiments of the present invention will be described in detail with reference to the accompanying drawings.
- [30] Fig. 3 is a perspective view showing an LED lamp according to an embodiment of the present invention, and Fig. 4 is a sectional view showing the LED lamp of Fig. 3.
- [31] As shown in Figs. 3 and 4, the LED lamp of this embodiment includes a plurality of LED packages 110, a PCB 120 for supplying power to the LED packages 110, and a heat dissipation plate 130 for dissipating heat, which is generated when the LED packages 110 emit light, to the outside.
- [32] Now, the respective components will be explained in greater detail.
- [33] Each of the LED packages 110 includes a metal slug 112 that is a kind of heat sink

having thermal conductivity, an LED chip 114 mounted to the metal slug 112 to generate various light according to properties of its material when power is applied in a forward direction, lead frames 116 for supplying power to the LED chip 114, and a molding portion 118 for protecting the LED chip 114.

[34] The metal slug 112 is to absorb and dissipate the heat generated from the LED chip 114. The metal slug 112 is generally made of a metallic material and formed to take the shape of a rectangular rod by means of molding. However, the shape of the metal slug 112 is not limited thereto but may be a variety of shapes such as a cylinder, an elliptical rod and a polygonal rod.

[35] A concave portion 113 depressed with a predetermined depth is formed at the center of an upper surface of the metal slug 112, and the LED chip 114 is mounted in the concave portion 113. The LED chip 114 mounted in the concave portion 113 is a horizontal type LED chip that has a two-tap wire structure using two wires 115 for connection to the pair of lead frames 116.

[36] In this embodiment, another member such as the metal slug 112 may be further provided together with the pair of lead frames 116. In this case where the metal slug 112 is further provided as mentioned above, there is an advantage in that the heat generated from the LED chip 114 can be rapidly dissipated to the outside.

[37] Although the LED chip 114 mounted in the concave portion 113 in this embodiment has been described by way of example as being a horizontal type LED chip, the present invention is not limited thereto but may employ various kinds of LED chips such as a vertical type LED chip. In addition, although the connection structure between the LED chip 114 and the lead frames 116 in this embodiment has been described by way of example as being a two-tap wire structure, the present invention is not limited thereto but may employ various structures such as a one-tap wire structure.

[38] Meanwhile, an insulation film 117 is provided near an edge of the metal slug 112 so as to insulate some portions of upper and side surfaces of the metal slug 112, and one end of each of the lead frames 116 is bonded to an upper portion of the insulation film 117. That is, one end of the lead frame 116 is bent along the upper and side surfaces of the metal slug 112, but the lead frame 116 is electrically isolated from the metal slug 112 due to the formation of the insulation film 117 therebetween.

[39] Here, although not shown in the figures, a recess is preferably formed in a lower surface of the metal slug 112 so that a portion of an elastic member 140, which will be explained later, can be inserted therein. In the case where a portion of the elastic member 140 is inserted into the metal slug 112 as mentioned above, it is possible to prevent the play of the metal slug 112 and to increase a contact area, resulting in more rapid heat dissipation.

[40] The PCB 120 is provided to supply power to the LED packages 110 while being

separated from the LED packages 110. In this embodiment, the PCB 120 comprises a pair of divided PCBs 120 and 120 that are spaced apart from each other so that the LED package 110 is exposed in a light emitting direction. The pair of divided PCBs 120 is arranged to be elongated in one direction and in parallel to each other, and placed on the pair of lead frames 116 provided in the LED package 110. Since the PCB 120 should supply power through the lead frames 116, a conductive pattern 122 is formed on a surface of the PCB 120 facing the lead frames, i.e., on a lower surface of the PCB 120, in this embodiment.

[41] In addition, at a region where the PCB 120 and the lead frame 116 are in contact with each other, a fixing hole 124 and a fixing member 119 that is to be at least partially inserted into the fixing hole 124 are formed. In this embodiment, the fixing member 119 is formed on the lead frame 116, and the fixing hole 124 is formed in the PCB 120.

[42] The fixing member 119 and the fixing hole 124 are means for ensuring that the lead frame 116 is in secure contact with the PCB 120. Preferably, the fixing member 119 is formed to protrude in a hemispherical shape, and the fixing hole 124 is formed as a circular through-hole. Further, most preferably, the fixing member 119 has a size greater than that of the fixing hole 124 so that only a portion of the fixing member 119 is inserted into the fixing hole 124.

[43] At this time, the positions of the fixing member 119 and the fixing hole 124 may be exchanged. That is, the fixing hole may be formed in the lead frame 116 and the fixing member 119 may be formed on the PCB 120.

[44] The heat dissipation plate 130 is formed to be elongated in the same direction as the PCB 120, and has a plurality of fixing shafts 132 formed on an upper surface thereof. Moreover, the elastic member 140 that is a kind of pressing means for elastically biasing the LED package 110 toward the PCB 120 is engaged with one of the fixing shafts 132.

[45] Upper and lower portions of the elastic member 140 are respectively brought into contact with the lower surface of the metal slug 112 of the LED package 110 and the heat dissipation plate 130, so that the heat generated from the LED chip 114 can be transferred to the heat dissipation plate 130. At this time, if a recess (not shown) into which a portion of the elastic member 140 is inserted is formed in the lower surface of the metal slug 112 as mentioned above, heat dissipation efficiency can be further improved. Further, it is possible to prevent the play of the LED package 110.

[46] As for a coupling structure of the LED lamp according to the present invention constructed as above, the heat dissipation plate 130 is provided at the lowermost position. As described above, the heat dissipation plate 130 is formed to be elongated in one direction (in a lengthwise direction of the PCB 120), and the plurality of fixing

shafts 132 are formed to protrude upward on the upper surface of the heat dissipation plate and at regular intervals in a lengthwise direction of the heat dissipation plate 130.

[47] In addition, the elastic member 140 is engaged with each of the fixing shafts 132, and the LED package 110 that is to come into contact with the elastic member 140 is positioned above the elastic member 140. At this time, the number of the LED packages 110 is identical to the number of the fixing shafts 132, and the upper portion of the elastic member is in contact with the metal slug 112 exposed below the LED package 110.

[48] Meanwhile, since the divided PCBs 120 in a pair are positioned respectively on the upper surfaces of the lead frames 116 in a pair, which protrude beyond both sides of the LED package 110, the lead frames 116 of the LED package 110 elastically biased upward by the elastic member 140 are brought into contact with the conductive pattern 122 formed on the lower surfaces of the divided PCBs 120.

[49] At this time, since the fixing hole 124 is formed in the PCB 120 and the fixing member 119 is formed on the lead frame 116 as mentioned above, the PCB and the lead frame can be in more secure contact with each other.

[50] In addition, even though external vibration is applied, the elastic member 140 absorbs the vibration so that the vibration cannot have influence on the LED package 110 or the PCB 120.

[51] Furthermore, with the above coupling structure, when only one LED package is out of order, it is possible to replace only the LED package. In addition, upon replacement of an LED package 110, it is sufficient to only separate the LED package 110 from the PCB 120, leading to easier replacement.

Mode for the Invention

[52] Here, the LED packages may be arranged in several rows rather than in one horizontal row, and one or two PCBs may be provided between rows of LED packages. In addition, in such arrangement, the LED packages may be mounted in alternate vertical rows. Although not described above, the LED lamp may be configured by means of various methods in addition to the aforementioned method. An example of LED lamps configured by means of the various methods, i.e., another embodiment of the present invention, is shown in the plan view of Fig. 5.

[53] Referring to Fig. 5, the LED lamp of this embodiment includes an opening portion 123 formed in a single PCB 120 so that LED packages 110 can be exposed in a light emitting direction, i.e., upward, contrary to the previous embodiment in which the divided PCBs 120 are provided to be spaced with each other. Although Fig. 5 shows that two LED packages 110 are exposed upward through the opening portion 123, the number of LED packages 110 is not specifically limited in the present invention.

- [54] Except that the structure in which the opening portion 123 is formed in the PCB 120 to expose the LED packages 110 upward, other structures of the LED lamp of this embodiment are substantially identical to those of the previous embodiment. Thus, detailed descriptions of the other structures will be omitted. Reference numerals of Fig. 5, which are denoted therein but have not been explained, designate components identical to those of the previous embodiment.

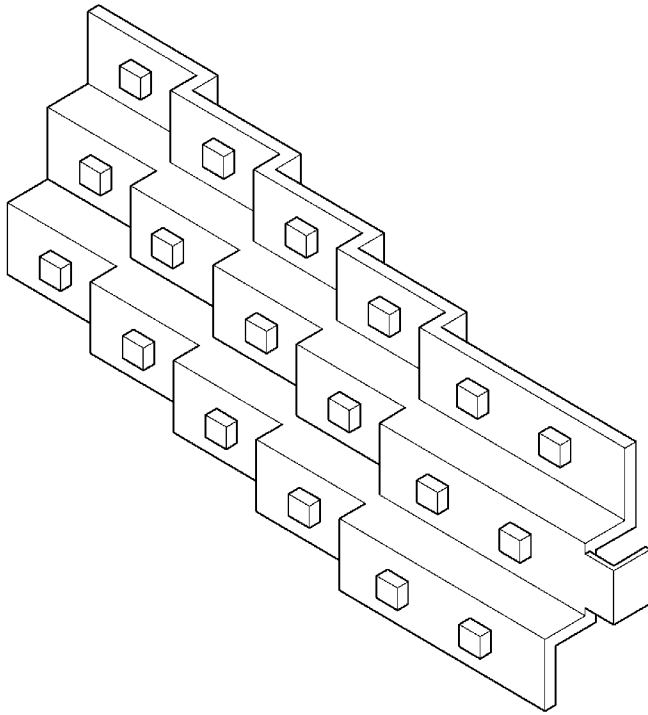
Industrial Applicability

- [55] Although the configurations and applications of the LED lamps according to preferred embodiments of the present invention have been described with reference to the accompanying drawings, it will be understood by those skilled in the art that the configurations and applications have been described only for illustrative purposes and various changes and modifications can be made thereto without departing from the spirit and scope of the invention.

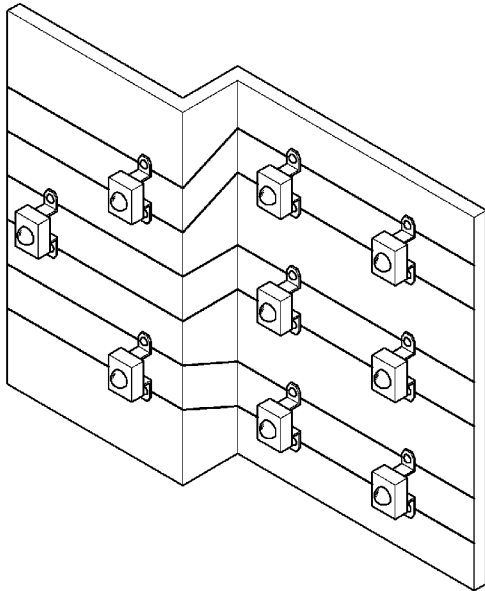
Claims

- [1] A light emitting diode (LED) lamp, comprising:
an LED package having a lead frame;
a printed circuit board separated from the LED package and having a conductive pattern formed on a surface thereof facing the lead frame; and
a pressing means for pressing the LED package toward the PCB so that the lead frame is in contact with the conductive pattern.
- [2] The LED lamp as claimed in claim 1, wherein a fixing hole is formed in one of the lead frame and the PCB, and a fixing member that is to be at least partially inserted into the fixing hole is formed on the other one of the lead frame and the PCB.
- [3] The LED lamp as claimed in claim 1 or 2, wherein a heat sink is formed on a lower surface of the LED package such that the heat sink is exposed outward, a heat dissipation plate is provided at a position spaced apart by a predetermined distance from the heat sink, and the pressing means is installed to be interposed between and brought contact with the heat sink and the heat dissipation plate.
- [4] The LED lamp as claimed in claim 1 or 2, wherein the pressing means comprises an elastic member.
- [5] The LED lamp as claimed in claim 3, wherein a fixing shaft for fixing the elastic member protrudes upward from an upper portion of the heat dissipation plate.
- [6] The LED lamp as claimed in claim 1, wherein the PCB comprises first and second PCBs that are separate from and spaced apart from each other so that the LED package is exposed in a light emitting direction.
- [7] The LED lamp as claimed in claim 1, wherein the PCB has an opening portion for exposing the LED package in a light emitting direction.

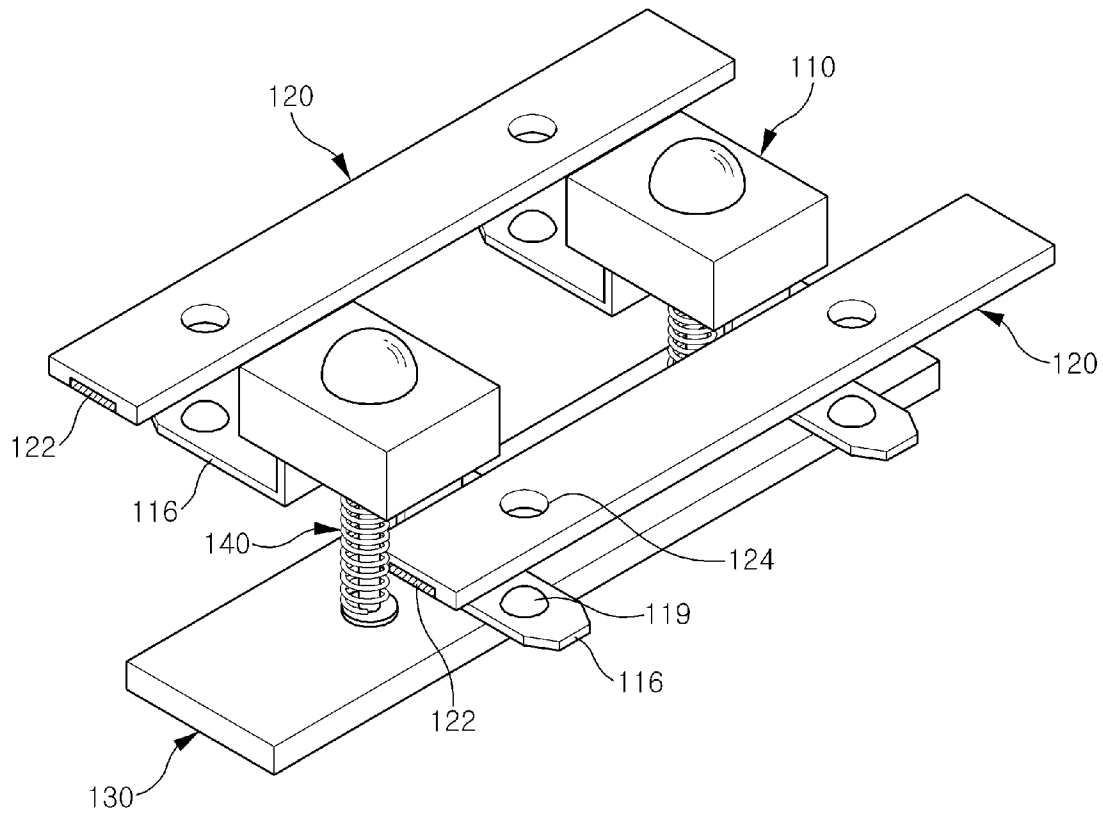
[Fig. 1]



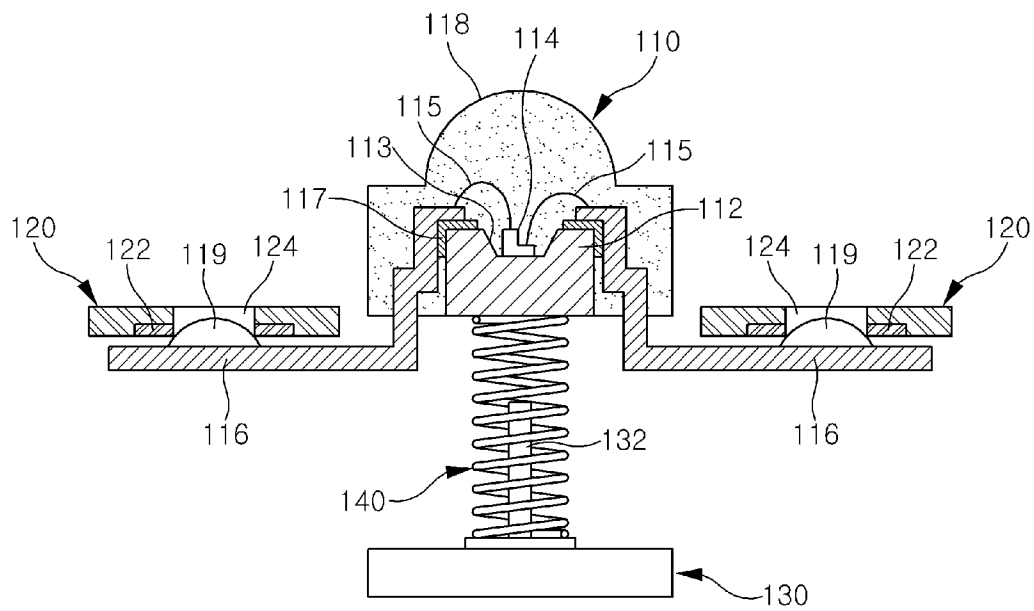
[Fig. 2]



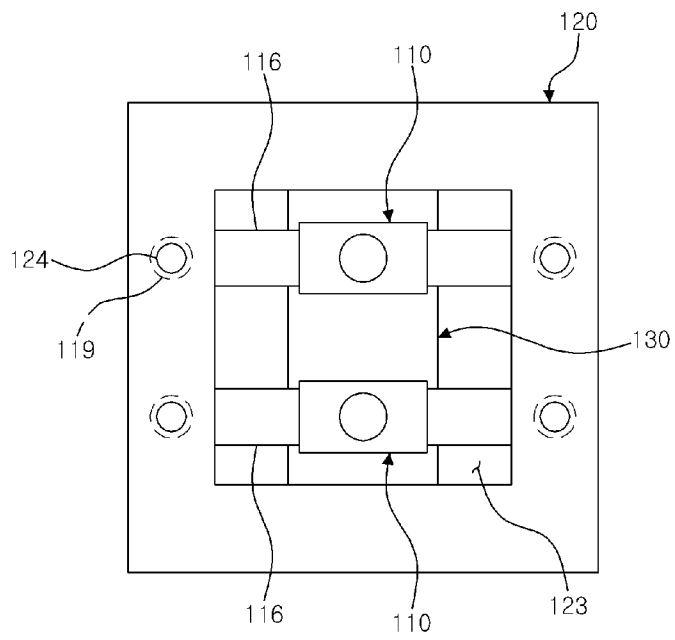
[Fig. 3]



[Fig. 4]



[Fig. 5]



INTERNATIONAL SEARCH REPORT

International application No.
PCT/KR2007/000171**A. CLASSIFICATION OF SUBJECT MATTER***F21S 2/00(2006.01)i*

According to International Patent Classification (IPC) or to both national classification and IPC

B. FIELDS SEARCHED

Minimum documentation searched (classification system followed by classification symbols)

IPC 8 F21V

Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched
KR, JP: IPC as aboveElectronic data base consulted during the international search (name of data base and, where practicable, search terms used)
eKIPASS(KIPO internal) "LED", "elastic" "press"**C. DOCUMENTS CONSIDERED TO BE RELEVANT**

Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
X	KR 10-2005-0119744 A (SAMSUNG ELECTRIC CO. LTD.) 22 December 2005	1, 4
Y	See abstrac and figure 4	2, 6
Y	KR 10-2003-0097277 A (HYUNDAI MOTORS CO. LTD.) 31 December 2003See abstrac and figures 3 and 4	2, 6
A	US 6345902 B2 (OHKOHDO, M.; SAKATA, H.) 12 February 2002 See abstrac and figures 2 and 3	1-7

☐ Further documents are listed in the continuation of Box C.☒ See patent family annex.

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Date of the actual completion of the international search

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INTERNATIONAL SEARCH REPORT

Information on patent family members

International application No.

PCT/KR2007/000171

Patent document cited in search report	Publication date	Patent family member(s)	Publication date
KR2005119744A	22.12.2005	NONE	
KR1020030097277	31.12.2003	NONE	
US06345902	12.02.2002	EP01002696A2	24.05.2000
		EP01002696A3	02.05.2002
		EP1002696A2	24.05.2000
		EP1002696A3	02.05.2002
		EP1002696A2	24.05.2000
		JP12151150	30.05.2000
		JP12207922	28.07.2000
		JP2000151150A2	30.05.2000
		JP2000207922A2	28.07.2000
		JP3807131B2	09.08.2006
		KR1020000034942	26.06.2000
		KR1020000052318	16.08.2000
		KR2000034942A	. .A
		KR2000052318A	. .A
		US06386733	14.05.2002
		US20010007526A1	12.07.2001
		US2001007526AA	12.07.2001
		US6345902BB	12.02.2002
		US6386733BA	14.05.2002